

Tool ID: 109  
Tool Location: 103

## Equipment Information Sheet MOS Metal Anneal 3 - C1

**Manager:** Phil Infante  
**Backup:** Aaron Windsor

607-254-4926  
607-254-4831

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

### SAFETY

- The furnaces are run at elevated temperatures of 400-1200°C and use flammable, toxic, and corrosive gases.

### USAGE RESTRICTIONS

- No changing of gas flows or process parameters without staff approval
- Max process temp of 1100 C

### SCHEDULING/SIGN-UP RESTRICTIONS

- Reservation blocks greater than 8 hrs must be cleared by a MOS staff person prior to reserving the time

Minimum Tool Time: 90  
minutes

### MATERIALS COMPATIBILITY CATEGORY

#### Tool Category 2: Silicon Based Substrates and Select Refractory Metals

Allowed	Not Allowed
Tool category 1/1E materials	No Glass Substrates
Silicon Based Materials only	No CNF Class A or Class B metals and oxides/compounds of (exposed or buried) (ie Magnesium, Zinc, Barium, Calcium)
Si, SiC, SiO <sub>2</sub> substrates	
All Furnace grown or deposited films	
PECVD Films	No Gold, Silver or Copper (Exposed or buried)
ALD dielectric films	No High Vapor pressure materials
<b>CNF Refractory Metals (ie Al, Ti, Ta, W, Pt, Mo, Cr, Ni)</b>	No III/V Compound Semiconductors
Nitrides and Oxides of above metals	No Organic/Biology Molecules prepared-with or without Salt buffers
Cured organics and baked Photoresist	

**High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.**

### Additional Material Restrictions and Exceptions

Last Updated: 03/20/2019